

Thyristor/Diode and Thyristor/Thyristor (ADD-A-PAK™ Generation 5 Power Modules), 27 A


ADD-A-PAK™

PRODUCT SUMMARY

| | |
|----------------------------|------|
| $I_{T(AV)}$ or $I_{F(AV)}$ | 27 A |
|----------------------------|------|

MECHANICAL DESCRIPTION

The Generation 5 of ADD-A-PAK™ modules combine the excellent thermal performance obtained by the usage of Direct Bonded Copper substrate with superior mechanical ruggedness, thanks to the insertion of a solid copper baseplate at the bottom side of the device. The Cu baseplate allows an easier mounting on the majority of heatsink with increased tolerance of surface roughness and improved thermal spread. The Generation 5 of AAP modules is manufactured without hard mold, eliminating in this way any possible direct stress on the leads.

The electrical terminals are secured against axial pull-out: they are fixed to the module housing via a click-stop feature already tested and proved as reliable on other Vishay HPP modules.

FEATURES

- High voltage
- Industrial standard package
- Thick copper baseplate
- UL E78996 approved
- 3500 V_{RMS} isolating voltage
- Totally lead (Pb)-free
- Designed and qualified for industrial level


**RoHS
COMPLIANT**

BENEFITS

- Up to 1600 V
- Fully compatible TO-240AA
- High surge capability
- Easy mounting on heatsink
- Al_2O_3 DBC insulator
- Heatsink grounded

ELECTRICAL DESCRIPTION

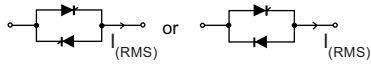
These modules are intended for general purpose high voltage applications such as high voltage regulated power supplies, lighting circuits, temperature and motor speed control circuits, UPS and battery chargers.

MAJOR RATINGS AND CHARACTERISTICS

| SYMBOL | CHARACTERISTICS | VALUES | UNITS |
|----------------------------|-----------------|-------------|-------------------|
| $I_{T(AV)}$ or $I_{F(AV)}$ | 85 °C | 27 | A |
| $I_{O(RMS)}$ | As AC switch | 60 | |
| I_{TSM} , I_{FSM} | 50 Hz | 400 | |
| | 60 Hz | 420 | |
| I^2t | 50 Hz | 800 | A ² s |
| | 60 Hz | 730 | |
| $I^2\sqrt{t}$ | | 8000 | A ² √s |
| V_{RRM} | Range | 400 to 1600 | V |
| T_{Stg} | | - 40 to 125 | °C |
| T_J | | | |

ELECTRICAL SPECIFICATIONS

| VOLTAGE RATINGS | | | | | |
|-----------------|--------------|--|---|--|---|
| TYPE NUMBER | VOLTAGE CODE | V _{RRM} , MAXIMUM REPETITIVE REVERSE VOLTAGE V | V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V | V _{DRM} , MAXIMUM REPETITIVE PEAK OFF-STATE VOLTAGE, GATE OPEN CIRCUIT V | I _{RRM} , I _{DRM} AT 125 °C mA |
| VSK.26 | 04 | 400 | 500 | 400 | 15 |
| | 06 | 600 | 700 | 600 | |
| | 08 | 800 | 900 | 800 | |
| | 10 | 1000 | 1100 | 1000 | |
| | 12 | 1200 | 1300 | 1200 | |
| | 14 | 1400 | 1500 | 1400 | |
| | 16 | 1600 | 1700 | 1600 | |

| ON-STATE CONDUCTION | | | | | |
|--|--------------------------------------|---|--|---|-------------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS |
| Maximum average on-state current (thyristors) | I _{T(AV)} | 180° conduction, half sine wave, T _C = 85 °C | | 27 | |
| Maximum average forward current (diodes) | I _{F(AV)} | | | | |
| Maximum continuous RMS on-state current as AC switch | I _{O(RMS)} |  | | 60 | A |
| Maximum peak, one-cycle non-repetitive on-state or forward current | I _{TSM} or I _{FSM} | t = 10 ms | No voltage reapplied | Sinusoidal half wave, initial T _J = T _J maximum | 400 |
| | | t = 8.3 ms | No voltage reapplied | | 420 |
| | | t = 10 ms | 100 % V _{RRM} reapplied | Initial T _J = T _J maximum | 335 |
| | | t = 8.3 ms | 100 % V _{RRM} reapplied | | 350 |
| | | t = 10 ms | T _J = 25 °C, no voltage reapplied | | 470 |
| | | t = 8.3 ms | T _J = 25 °C, no voltage reapplied | | 490 |
| Maximum I ² t for fusing | I ² t | t = 10 ms | No voltage reapplied | Initial T _J = T _J maximum | 800 |
| | | t = 8.3 ms | No voltage reapplied | | 730 |
| | | t = 10 ms | 100 % V _{RRM} reapplied | Initial T _J = T _J maximum | 560 |
| | | t = 8.3 ms | 100 % V _{RRM} reapplied | | 510 |
| | | t = 10 ms | T _J = 25 °C, no voltage reapplied | | 1100 |
| | | t = 8.3 ms | T _J = 25 °C, no voltage reapplied | | 1000 |
| Maximum I ² √t for fusing | I ² √t ⁽¹⁾ | t = 0.1 to 10 ms, no voltage reapplied | | 8000 | A ² √s |
| Maximum value or threshold voltage | V _{T(TO)} ⁽²⁾ | Low level ⁽³⁾ | T _J = T _J maximum | 0.92 | V |
| | | High level ⁽⁴⁾ | | 0.95 | |
| Maximum value of on-state slope resistance | r _t ⁽²⁾ | Low level ⁽³⁾ | T _J = T _J maximum | 12.11 | mΩ |
| | | High level ⁽⁴⁾ | | 11.82 | |
| Maximum peak on-state or forward voltage | V _{TM} | I _{TM} = π × I _{T(AV)} | T _J = 25 °C | 1.95 | V |
| | V _{FM} | I _{FM} = π × I _{F(AV)} | | | |
| Maximum non-repetitive rate of rise of turned on current | di/dt | T _J = 25 °C, from 0.67 V _{DRM} , I _{TM} = π × I _{T(AV)} , I _g = 500 mA, t _r < 0.5 μs, t _p > 6 μs | | 150 | A/μs |
| Maximum holding current | I _H | T _J = 25 °C, anode supply = 6 V, resistive load, gate open circuit | | 200 | mA |
| Maximum latching current | I _L | T _J = 25 °C, anode supply = 6 V, resistive load | | 400 | |

Notes

(1) I²t for time t_x = I²√t × √t_x

(2) Average power = V_{T(TO)} × I_{T(AV)} + r_t × (I_{T(RMS)})²

(3) 16.7 % × π × I_{AV} < I < π × I_{AV}

(4) I > π × I_{AV}



| TRIGGERING | | | | | |
|--|-------------|---|-----------------------------------|--------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS |
| Maximum peak gate power | P_{GM} | | | 10 | W |
| Maximum average gate power | $P_{G(AV)}$ | | | 2.5 | |
| Maximum peak gate current | I_{GM} | | | 2.5 | A |
| Maximum peak negative gate voltage | $-V_{GM}$ | | | 10 | V |
| Maximum gate voltage required to trigger | V_{GT} | $T_J = -40\text{ °C}$ | Anode supply = 6 V resistive load | 4.0 | |
| | | $T_J = 25\text{ °C}$ | | 2.5 | |
| | | $T_J = 125\text{ °C}$ | | 1.7 | |
| Maximum gate current required to trigger | I_{GT} | $T_J = -40\text{ °C}$ | Anode supply = 6 V resistive load | 270 | mA |
| | | $T_J = 25\text{ °C}$ | | 150 | |
| | | $T_J = 125\text{ °C}$ | | 80 | |
| Maximum gate voltage that will not trigger | V_{GD} | $T_J = 125\text{ °C}$, rated V_{DRM} applied | | 0.25 | V |
| Maximum gate current that will not trigger | I_{GD} | $T_J = 125\text{ °C}$, rated V_{DRM} applied | | 6 | mA |

| BLOCKING | | | | | |
|---|--------------------------|--|--|----------------------------|------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS |
| Maximum peak reverse and off-state leakage current at V_{RRM} , V_{DRM} | I_{RRM} , I_{DRM} | $T_J = 125\text{ °C}$, gate open circuit | | 15 | mA |
| RMS insulation voltage | V_{INS} | 50 Hz, circuit to base, all terminals shorted | | 2500 (1 min) 3500 (1 s) | V |
| Maximum critical rate of rise of off-state voltage | $dV/dt^{(1)}$ | $T_J = 125\text{ °C}$, linear to $0.67 V_{DRM}$ | | 500 | V/ μ s |

Note

(1) Available with $dV/dt = 1000\text{ V/ms}$, to complete code add S90 i.e. VSKT26/16AS90

| THERMAL AND MECHANICAL SPECIFICATIONS | | | | | |
|--|-------------------|--|--|-------------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS |
| Junction operating and storage temperature range | T_J , T_{Stg} | | | - 40 to 125 | °C |
| Maximum internal thermal resistance, junction to case per module | R_{thJC} | DC operation | | 0.31 | K/W |
| Typical thermal resistance, case to heatsink | R_{thCS} | Mounting surface flat, smooth and greased | | 0.1 | |
| Mounting torque $\pm 10\%$ | to heatsink | A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. | | 5 | Nm |
| | busbar | | | 3 | |
| Approximate weight | | | | 110 | g |
| | | | | 4 | oz. |
| Case style | | JEDEC | | TO-240AA | |

| ΔR CONDUCTION PER JUNCTION | | | | | | | | | | | |
|------------------------------------|---------------------------|------|------|------|------|-----------------------------|------|------|------|------|-------|
| DEVICES | SINE HALF WAVE CONDUCTION | | | | | RECTANGULAR WAVE CONDUCTION | | | | | UNITS |
| | 180° | 120° | 90° | 60° | 30° | 180° | 120° | 90° | 60° | 30° | |
| VSK.26 | 0.23 | 0.27 | 0.34 | 0.48 | 0.73 | 0.17 | 0.28 | 0.36 | 0.49 | 0.73 | °C/W |

Note

- Table shows the increment of thermal resistance R_{thJC} when devices operate at different conduction angles than DC

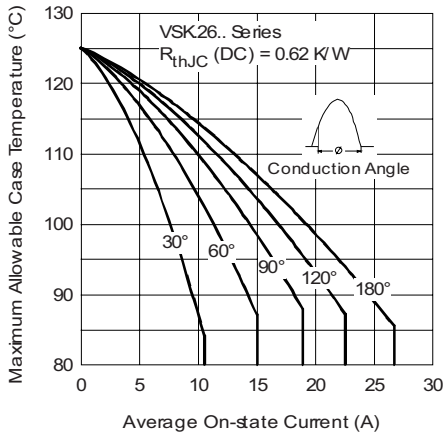


Fig. 1 - Current Ratings Characteristics

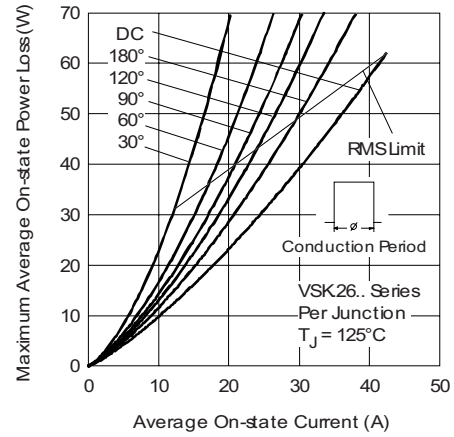


Fig. 4 - On-State Power Loss Characteristics

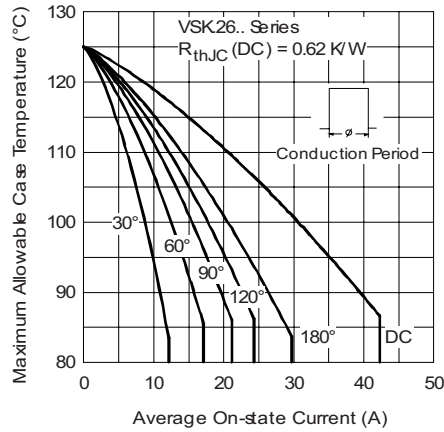


Fig. 2 - Current Ratings Characteristics

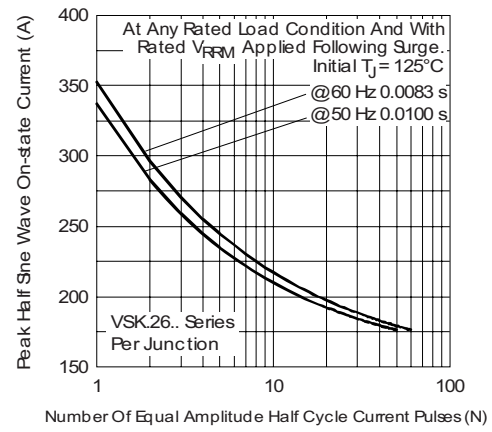


Fig. 5 - Maximum Non-Repetitive Surge Current

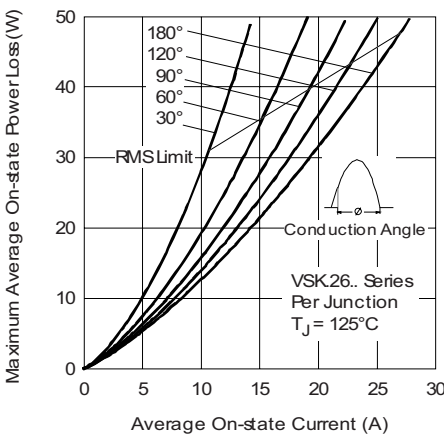


Fig. 3 - On-State Power Loss Characteristics

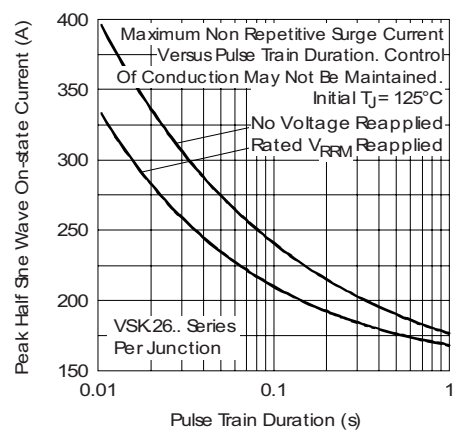


Fig. 6 - Maximum Non-Repetitive Surge Current

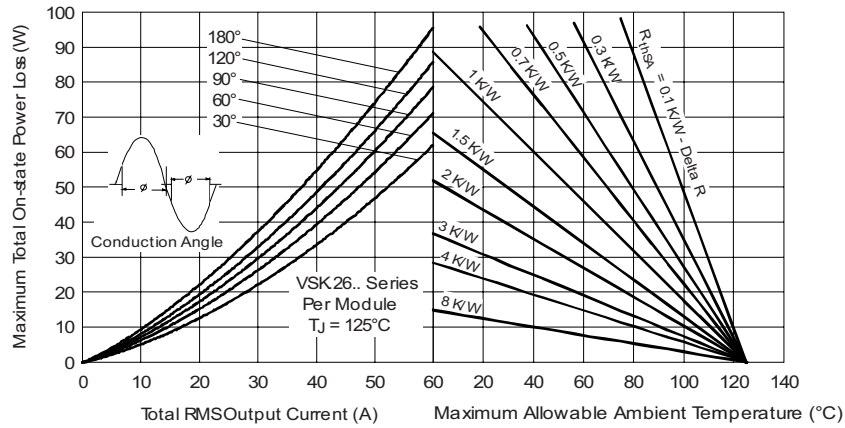


Fig. 7 - On-State Power Loss Characteristics

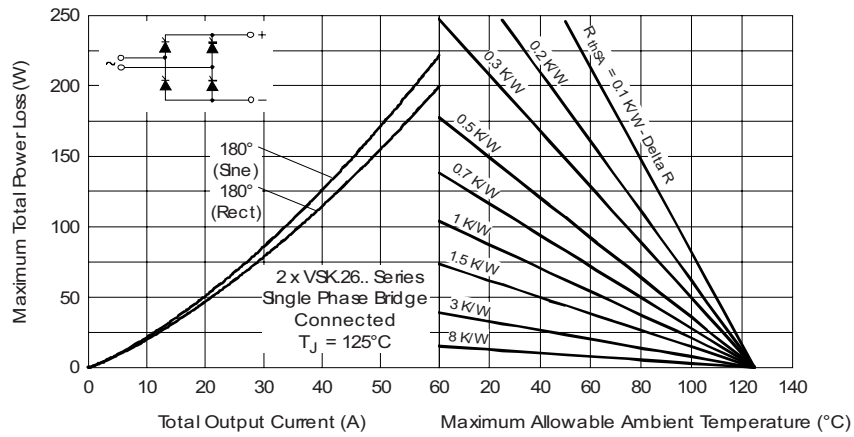


Fig. 8 - On-State Power Loss Characteristics

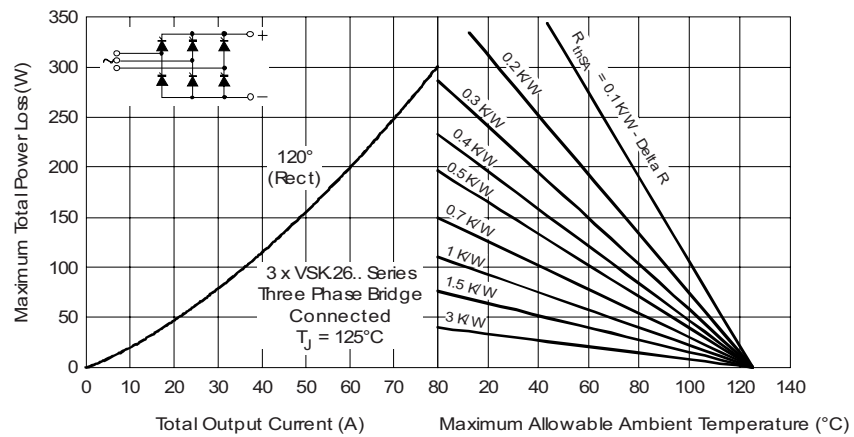


Fig. 9 - On-State Power Loss Characteristics

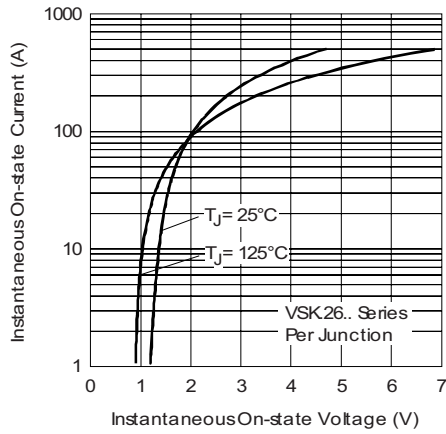


Fig. 10 - On-State Voltage Drop Characteristics

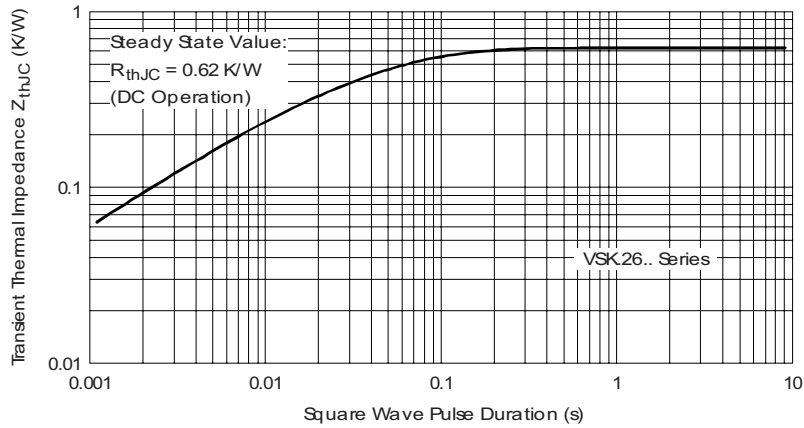


Fig. 11 - Thermal Impedance Z_{thJC} Characteristics

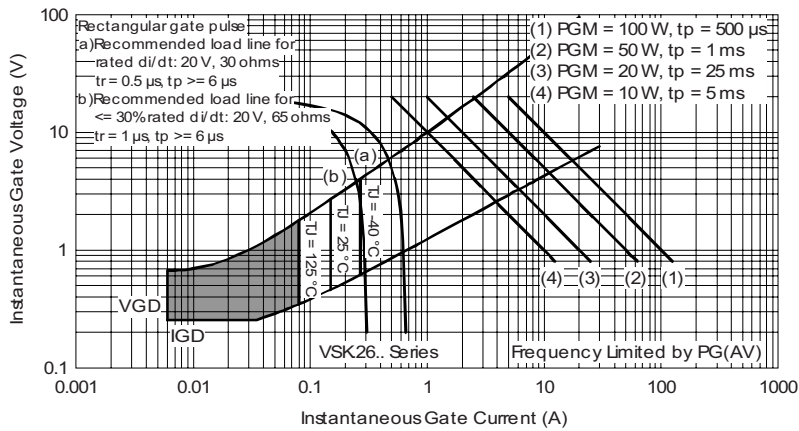


Fig. 12 - Gate Characteristics



ORDERING INFORMATION TABLE

| | | | | | | | |
|-------------|------------|----------|-----------|----------|-----------|------------|----------|
| Device code | VSK | T | 26 | / | 16 | S90 | P |
| | ① | ② | ③ | | ④ | ⑤ | ⑥ |

- 1** - Module type
- 2** - Circuit configuration (see end of datasheet)
- 3** - Current code ⁽¹⁾
- 4** - Voltage code (see Voltage Ratings table)
- 5** - dV/dt code: S90 = dV/dt 1000 V/μs
No letter = dV/dt 500 V/μs
- 6** - P = Lead (Pb)-free

⁽¹⁾ Available with no auxiliary cathode

(for details see dimensions - link at the end of datasheet)

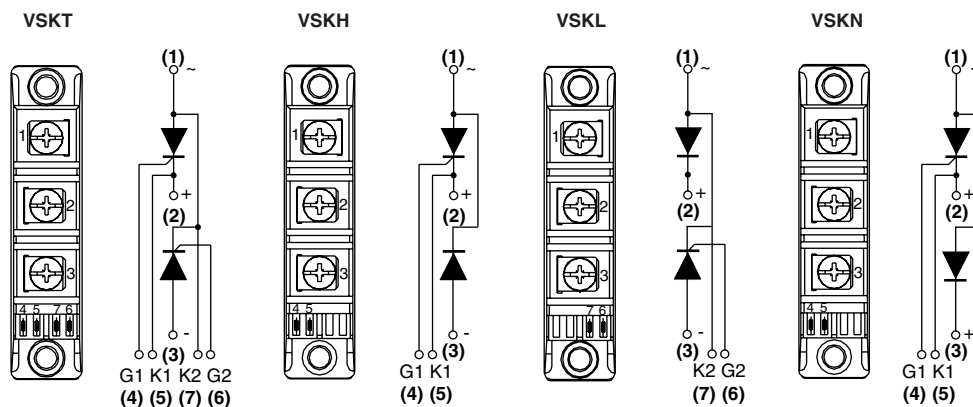
To specify change: 26 to 27

e.g.: VSKT27/16P etc.

Note

- To order the optional hardware go to www.vishay.com/doc?95172

CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS

| | |
|------------|---|
| Dimensions | http://www.vishay.com/doc?95085 |
|------------|---|



Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.